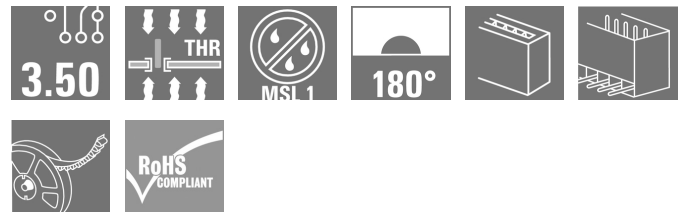


SL-SMT 3.50/10/180G 3.2SN BK RL**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**Product image**

High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**

General ordering data

| | |
|--------------|--|
| Version | PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.50 mm, Number of poles: 10, 180°, Solder pin length (l): 3.2 mm, tinned, black, Tape |
| Order No. | 1934650000 |
| Type | SL-SMT 3.50/10/180G 3.2SN BK RL |
| GTIN (EAN) | 4032248591565 |
| Qty. | 265 pc(s). |
| Product data | IEC: 320 V / 15 A UL: 300 V / 10 A |
| Packaging | Tape |

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Technical data**Dimensions and weights**

| | | | |
|--------------------------|------------|-----------------|------------|
| Depth | 7.5 mm | Depth (inches) | 0.295 inch |
| Height | 14.3 mm | Height (inches) | 0.563 inch |
| Height of lowest version | 11.1 mm | Width | 36.4 mm |
| Width (inches) | 1.433 inch | Net weight | 4.92 g |

System specifications

| | | | |
|--|--|--|------------------------------|
| Product family | OMNIMATE Signal - series BL/SL 3.50 | Type of connection | Board connection |
| Mounting onto the PCB | THT/THR solder connection | Pitch in mm (P) | 3.5 mm |
| Pitch in inches (P) | 0.138 " | Outgoing elbow | 180° |
| Number of poles | 10 | Number of solder pins per pole | 1 |
| Solder pin length (l) | 3.2 mm | Solder pin length tolerance | 0 / -0.3 mm |
| Solder pin dimensions | d = 1.2 mm, Octagonal | Solder pin dimensions = d tolerance | 0 / -0.03 mm |
| Solder eyelet hole diameter (D) | 1.4 mm | Solder eyelet hole diameter tolerance (D)+ | 0.1 mm |
| Outside diameter of solder pad | 2.3 mm | Template aperture diameter | 2.1 mm |
| L1 in mm | 31.5 mm | L1 in inches | 1.24 " |
| Number of rows | 1 | Pin series quantity | 1 |
| Touch-safe protection acc. to DIN VDE 57 106 | finger-safe plugged/ back-of-hand-safe unplugged | Touch-safe protection acc. to DIN VDE 0470 | IP20 plugged/ IP10 unplugged |
| Volume resistance | ≤5 mΩ | Can be coded | Yes |
| Plugging force/pole, max. | 6 N | Pulling force/pole, max. | 6 N |

Material data

| | | | |
|---------------------------------------|---------------------------|---------------------------------------|---------------------------|
| Insulating material | LCP GF | Colour | black |
| Colour chart (similar) | RAL 9011 | Insulating material group | IIla |
| Comparative Tracking Index (CTI) | ≥ 175 | Moisture Level (MSL) | 1 |
| UL 94 flammability rating | V-0 | Contact material | Cu-alloy |
| Contact surface | tinned | Layer structure of solder connection | 2...3 μm Ni / 5...7 μm Sn |
| Layer structure of plug contact | 2...3 μm Ni / 5...7 μm Sn | Storage temperature, min. | -40 °C |
| Storage temperature, max. | 70 °C | Operating temperature, min. | -50 °C |
| Operating temperature, max. | 100 °C | Temperature range, installation, min. | -30 °C |
| Temperature range, installation, max. | 100 °C | | |

Rated data acc. to IEC

| | | | |
|---|------------------------|---|-------------------|
| tested acc. to standard | IEC 60664-1, IEC 61984 | Rated current, min. number of poles (Tu=20°C) | 15 A |
| Rated current, max. number of poles (Tu=20°C) | 12 A | Rated current, min. number of poles (Tu=40°C) | 13 A |
| Rated current, max. number of poles (Tu=40°C) | 10 A | Rated voltage for surge voltage class / pollution degree II/2 | 320 V |
| Rated voltage for surge voltage class / pollution degree III/2 | 160 V | Rated voltage for surge voltage class / pollution degree III/3 | 160 V |
| Rated impulse voltage for surge voltage class/ pollution degree II/2 | 2.5 kV | Rated impulse voltage for surge voltage class/ pollution degree III/2 | 2.5 kV |
| Rated impulse voltage for surge voltage class/ contamination degree III/3 | 2.5 kV | Short-time withstand current resistance | 3 x 1s with 100 A |

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Technical data

Rated data acc. to CSA

Institute (CSA)



Certificate No. (CSA)

200039-1176845

Rated voltage (Use group B / CSA) 300 V

Rated voltage (Use group D / CSA) 300 V

Rated current (Use group B / CSA) 10 A

Rated current (Use group D / CSA) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Rated data acc. to UL 1059

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 10 A

Rated current (Use group D / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Packing

ESD Level packaging static dissipative

VPE length 330 mm

VPE height 60 mm

Tape width (W) 56 mm

Tape pocket height (AO) 7.8 mm

Tape pocket separation (P1) 16 mm

Tape pocket separation (F) 26.2 mm

Surface resistance $R_s = 10^9 - 10^{12} \Omega$ Length Pick & Place Pad (L_{PPP}) 12.65 mmProtrusion 1 Pick & Place Pad ($L_{01 (PPP)}$) 2.7 mm

Packaging Tape

VPE width 330 mm

Tape depth (T2) 16.5 mm

Tape pocket depth (KO) 16 mm

Tape pocket width (BO) 43.7 mm

Tape hole separation (E) 1.75 mm

Tape reel diameter ϕ (A) 330 mmWidth Pick & Place Pad (W_{PPP}) 6.8 mmDiameter of the withdrawal surface (ϕ D_{max}) 5 mmProtrusion 2 Pick & Place Pad ($P_{02 (PPP)}$) 2.5 mm

Classifications

ETIM 6.0 EC002637

ETIM 7.0 EC002637

ETIM 8.0 EC002637

ETIM 9.0 EC002637

ECLASS 9.0 27-44-04-02

ECLASS 9.1 27-44-04-02

ECLASS 10.0 27-44-04-02

ECLASS 11.0 27-46-02-01

ECLASS 12.0 27-46-02-01

ECLASS 13.0 27-46-02-01

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www.weidmueller.com**Technical data****Important note**

| | |
|----------------|---|
| IPC conformity | Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request. |
| Notes | <ul style="list-style-type: none"> • Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet $D = 1.4 \pm 0.1 \text{ mm}$ • Solder eyelet diameter $D = 1.5 \pm 0.1 \text{ mm}$, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load • Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months |

Approvals

Approvals



| | |
|-----------------------|------------|
| ROHS | Conform |
| UL File Number Search | UL Website |
| Certificate No. (UR) | E60693 |

Downloads

| | |
|--------------------------------------|---|
| Engineering Data | CAD data – STEP |
| Product Change Notification | PCN_2015_208_PL30X_SC-SMT_SL_SMT_3.xx_5.xx_neue_Tapeverpackung_Step_3_DE PCN_2015_208_PL30X_SC-SMT_SL_SMT_3.xx_5.xx_new_Tape_Packaging_Step_3_EN Changeover to ESD bags for "Tape on Reel" products Umstellung auf ESD-Beutel bei „Tape on Reel“ Produkten |
| Catalogues | Catalogues in PDF-format |
| Brochures | FL DRIVES EN FL DRIVES DE |
| White paper surface mount technology | Download Whitepaper |

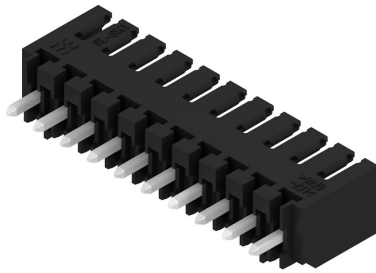
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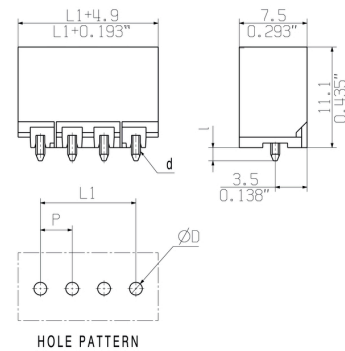
www.weidmueller.com

Drawings

Product image



Dimensional drawing



Dimensional drawing



Dimensional drawing



Example of use



Recommended wave soldering profiles

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Germany
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Fax: +49 5231 14-292083
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.